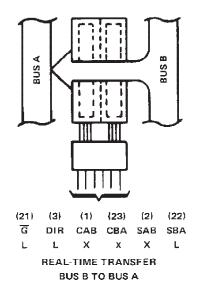
SN54LS846 THRU SN54LS649 SN74LS646 THRU SN74LS649 OCTAL BUS TRANSCEIVERS AND REGISTERS SDLS190A - DECEMBER 1982 - REVISED MAY 2004

- Independent Registers for A and B Buses
- Multiplexed Real-Time and Stored Data
- Choice of True or Inverting Data Paths
- Choice of 3-State or Open-Collector Outputs
- Included Among the Package Options Are Compact 24-pin 300-mil-Wide Plastic and Ceramic DIPs, Ceramic Chip Carriers, and Plastic "Small Outline" Packages
- Dependable Texas Instruments Quality and Reliability

DEVICE	OUTPUT	LOGIC
'LS646	3-State	True
'LS647	Open-Collector	True
'LS648	3-State	Inverting
'LS649	Open-Collector	Inverting

description

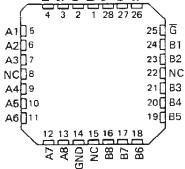
These devices consist of bus transceiver circuits with 3-state or open-collector outputs, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus will be clocked into the registers on the low-to-high transition of the appropriate clock pin (CAB or CBA). The following examples demonstrate the four fundamental bus-management functions that can be performed with the octal bus transceivers and registers.

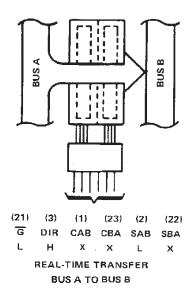


SN54LS' JT PACKAGE
SN74LS' DW OR NT PACKAGE
(TOP VIEW)

CAB SAB DIR A1 A2 A3 A4 A5 A6 A7 A8	1 2 3 4 5 6 7 8 9 10 11	24 23 22 21 20 19 18 17 16 15 14	VCC CBA SBA G B1 B2 B3 B4 B5 B6 B6 B7
A8 GND	11 12	14 	B7 B8









Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

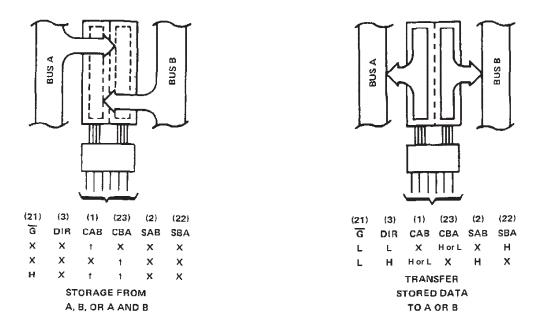
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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SN54LS646 THRU SN54LS649, SN74LS646 THRU SN74LS649 OCTAL BUS TRANSCEIVERS AND REGISTERS

SDLS190A - DECEMBER 1982 - REVISED MAY 2004



Enable (\overline{G}) and direction (DIR) pins are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select controls (SAB and SBA) can multiplex stored and real-time (transparent mode) data. The direction control determines which bus will receive data when enable \overline{G} is active (low). In the isolation mode (control \overline{G} high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

The SN54' family is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74' family is characterized for operation from 0° to 70°C.

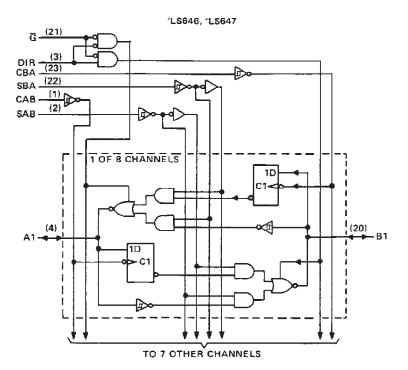
		INPU	'S			DATA	A 1/0†	OPERATION OR FUNCTION				
G	DIR	CAB	CBA	SAB	SBA	A1 THRU A8	B1 THRU B8	LS646, LS647	LS648, LS649			
X	Х	t	×	x	Х	Input	Not specified	Store A, B unspecified	Store A, B unspecified			
х	X	X	1	х	х	Not specified	Input	Stare B, A unspecified	Store B, A unspecified			
н	х	t	†	х	Х	Input	Input	Store A and B Data	Store A and B Data			
н	Х	H or L	HorL	Х	x	mpur	Input	Isolation, hold storage	Isolation, hold storage			
L	L	х	х	X	L	Butaut		Reat-Time 8 Data to A Bus	Real-Time B Data to A Bus			
L	L	х	H or L	Х	н	Output	Input	Stored B Data to A Bus	Stored B Data to A Bus			
Ł	H	х	x	L	X	t	0	Real-Time A Data to B Bus	Real-Time A Data to B Bus			
L	н	H or L	х	н	х	fnput	Output	Stored A Data to B Bus	Stored A Data to B Bus			

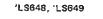
FUNCTION TABLE

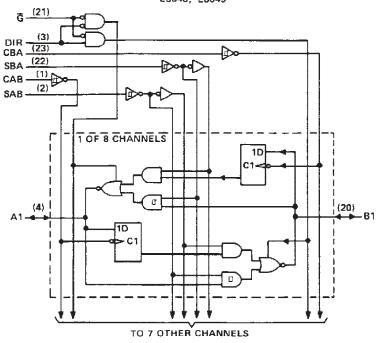
[†] The data output functions may be enabled or disabled by various signals at the G and DIR inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs.



logic diagrams (positive logic)





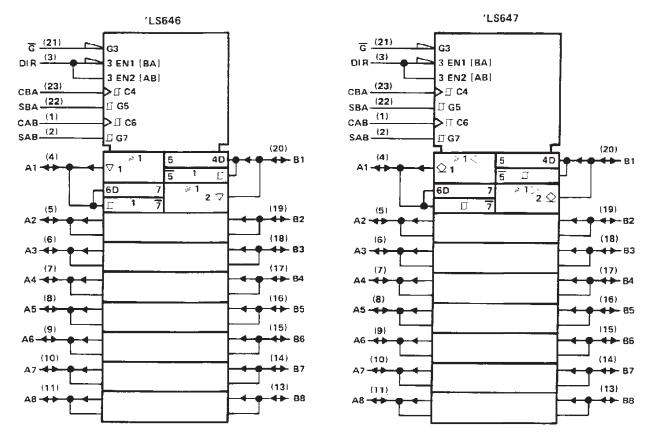


Pin numbers shown are for DW, JT, and NT packages.



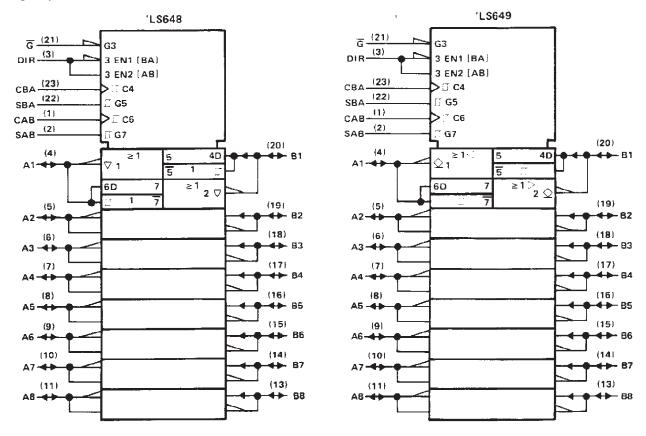
SN54LS646, SN54LS647, SN74LS646, SN74LS647 OCTAL BUS TRANSCEIVERS AND REGISTERS SDLS190A – DECEMBER 1982 – REVISED MAY 2004

logic symbols[†]



[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, JT, and NT packages.





logic symbols[†] (continued)

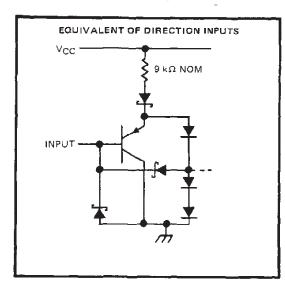
[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, JT, and NT packages.

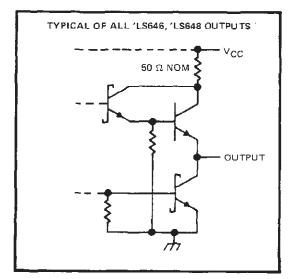


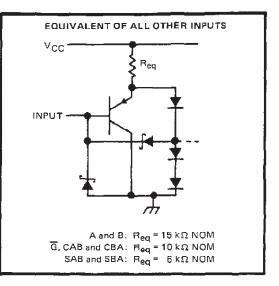
SN54LS646 THRU SN54LS649 SN74LS646 THRU SN74LS649 OCTAL BUS TRANSCEIVERS AND REGISTERS SDLS190A - DECEMBER 1982 - REVISED MAY 2004

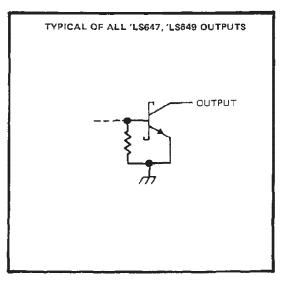
50130A - DECEMBER 1302 - REVISED MAT 2004

schematics of inputs and outputs











SN54LS646, SN54LS648, SN74LS646, SN74LS648 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS SDLS190A – DECEMBER 1982 – REVISED MAY 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC}	,
Input voltage: Control inputs	
Operating free-air temperature range:	SN54LS646, SN54LS648 55°C to 125°C
	SN74LS646, SN74LS648 0°C to 70°C
Storage temperature range	$-65^{\circ}C$ to $150^{\circ}C$

recommended operating conditions

			SN	54LS640	5/648	SN7	UNIT		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage			8 - E -	0.5			0.6	V
юн	High-level output current				- 12			- 15	mA
IOL	Low-level output current				12			24	mA
		CBA or CAB high	15			15			
t _w	Pulse duration	CBA or CAB low	30			30			ns
		Data high or low	30			30		-	
	Setup time	A		_					
t _{su}	before CAB1 or CBA1	A or B	15			15			ns
•.	Hold time							-	
^t h	after CAB† or CBA†	A or B .	0			0			ns
TA	Operating free-air temperature	Operating free-air temperature			125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAN	ETED		TEST CONDIT	IONE [†]	SN5	i4LS646	/648	SN7	4LS646	/648	UNIT		
FARAIV	IETER		TEST CONDIT	IUNSI	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT		
VIK		V _{CC} = MIN,	lj = — 18 mA				- 1.5	T		- 1.5	V		
Hysteresis (V _{T+} –V _T _)	A or B input	V _{CC} = MIN			0.1	0.4		0.2	0.4		v		
		V _{CC} = MIN,	$\chi_{111} = 2\chi$	I _{OH} = - 3 mA	2.4	3.4		2.4	3.4				
⊻он		V _{IL} = MAX	VIH - 2 V,	I _{OH} = - 12 mA	2						v		
				I _{ОН} = 15 mA				2					
Vol		Vcc = MIN,	V _{1H} = 2 V,	loL = 12 mA		0.25	0.4		0.25	0.4	v		
		V _{IL} = MAX		I _{OL} = 24 mA					0.35	0.5	0.5		
Ц	Control inputs	V _{CC} = MAX,	V = 7 V				0.1			0,1	- mA		
· · · · · · · · · · · · · · · · · · ·	A or B ports	V _{CC} = MAX,	V _I = 5.5 V				0.1			0.1			
ηн	Control inputs	V _{CC} = MAX,	V1=27V				20			20	UA		
	A or B ports		• 1 2.7 •				20			20			
ЦL	Control inputs	Voo = MAX	$V_{1} = 0.4 V$				- 0.4			- 0.4	mA		
	A or B ports		$V_{CC} = MAX, V_1 = 0.4 V$				- 0.4			- 0.4			
los§		V _{CC} = MAX,	V _O = 0 V		- 40		- 225	- 40		- 225	mA		
				Outputs high		91	145		91	145			
	L\$646			Outputs low		103	165		103	165			
^I cc		$V_{00} = MAX$		Outputs disabled		103	165		103	165	mA		
·		V _{CC} = MAX		Outputs high		. 91	145		91	145	U/A		
	LS648			Outputs low		103	165		103	165			
				Outputs disabled		120	180		120	180			

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 ‡ All typical values are at V_CC = 5 V, T_A = 25 °C.

⁵ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

 \P For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current,



SN54LS646, SN54LS648, SN74LS646, SN74LS648 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS SDLS190A - DECEMBER 1982 - REVISED MAY 2004

	FROM	то		1	LS646		1	LS648		
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
^t PLH	CAB or CBA	A or B			15	25		15	25	ns
^t PHL	CAD OF CDA	Auro			23	35		24	40	ns
tplh	A or B	B or A			12	18		12	18	ns
^t PHL	AOLP	BUR			13	20		15	25	កទ
^t PLH	SAB or SBA [†] with Bus				26	40		37	55	ns
tPHL	input high	A or B	R _L = 667 Ω. C _L = 45 pF,		21	35		24	40	ns
^t PLH	SAB or SBA [†] with Bus	AOL	See Note 2		33	50		26	40	ns
^t PHL	input low				14	25		23	40	nş
^t PZH	ि				33	55		30	50	ns
^t PZ1	G	A or B			42	65		37	55	ns
^t PZH		AULE			28	45		23	40	пŝ
TPZL	DIR				39	60		30	45	nş
^t PHZ	G				23	35		28	45	ns
TPLZ	G	A	RL=667Ω, CL=5pF,		22	35		22	35	nş
TPHZ	DIR	A or B	See Note 2		20	30		24	35	nŝ
^t PLZ					19	30		19	30	ns

switching characteristics, V_{CC} = 5 V, $T_A = 25^{\circ}C$

[†] These parameters are measured with the internal output state of the storage register opposite to that of the input. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



SN54LS647, SN54LS649, SN74LS647, SN74LS649 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH OPEN-COLLECTOR OUTPUTS SDLS190A - DECEMBER 1982 - REVISED MAY 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
Input voltage (control inputs)	
Off-state output voltage (A and B ports)	5.5 V
Operating free-air temperature range: SN	54LS647, SN54LS649
S	74LS647, SN74LS649
Storage temperature range	-65° C to 150° C

recommended operating conditions

				N64LS6			N74LS6		UNIT	
			8	N54LS6	49	s	N74LS6	549		
			MIN	NOM	MAX	MIN	NOM	MAX		
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V	
ViH	High-level input voltage		2			2			V	
VIL	Low-level input voltage				0.5			0.6	V	
√он	High-level output voltage				5.5			5.5	V	
10L	Low-level output voltage				12			24	mA	
		CBA or CAB high	15			15				
^t w	Pulse duration	CBA or CAB low	30			30			ns	
	Γ	Data high or low	30			30				
t _{su}	Setup time before CAB t or CBA t	A or B	15	· ·· ··		15			N 5	
th	Hold time after CAB1 or CBA1	A or B	0		•	0			N 5	
TA	Operating free-air temperat	ure	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS [†]		SN54LS647 SN54LS649			SN74LS647 SN74LS649			UNIT
					TYP‡	MAX	MIN TYPE M	MAX		
VIK		V _{CC} = MIN, I ₁ = - 18 mA				- 1.5			- 1.5	V
Hysteresis (V _{T+} –V _T _)	A or B input	V _{CC} = MIN		0.1	0.4		0.2	0.4		v
łон	•	V _{CC} = MIN, V _{IH} = 2 V, V _{OH} = 5.5 V	V _{IL} = MAX,			0.1			0.1	mА
VOL		$V_{CC} = MIN, V_{IH} = 2 V,$ $V_{IL} = MAX$	IOL = 12 mA		0.25	0.4		0.25 0.35	0.4 0.5	v
1.	A or B		V ₁ = 5.5 V	1		0.1	T		0.1	
11	All others	V _{CC} = MAX	V1 = 7 V	0.1					0.1	mA
Чн		V _{CC} = MAX, V _I = 2.7 V	•			20	1		20	μA
ΗL.		V _{CC} = MAX, V ₁ = 0.4 V				- 0.4	1		- 0.4	mA
	'LS647		Outputs high		79	130	[79	130	
laa		V _{CC} = MAX, Outputs open	Outputs low		94	150	T	94	150	
lcc	'L\$649		Outputs high		79	130		79	130	mΑ
	L3049	V _{CC} = MAX, Outputs open	Outputs low		94	150		94	150	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

I All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.



SN54LS647, SN54LS649, SN74LS647, SN74LS649 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH OPEN-COLLECTOR OUTPUTS SDLS190A - DECEMBER 1982 - REVISED MAY 2004

PARAMETER	FROM	то	TEST CONDUTIONS	['LS647			'L\$649		
	(INPUT)		TEST CONDITIONS	MIN	ТҮР	MAX	MIN	TYP	MAX	UNIT
^t PLH	CAB or CBA	A or B			22	35		17	30	ns
^t PHL	CAB OF CBA	AOLD			28	45		28	45	ភទ
трцн	AorB	B or A		[17	26		15	25	ns
^t PHL		BURA			18	27		20	30	ns
^t PLH	SAB or SBA [†]				33	50		37	55	ns
^t PHL	with Bus input high	A or B	RL=667Ω, CL=45pF,		29	45		28	45	۳s
^t PLH	SAB or SBA [†] with Bus	AorB	See Note 2		39	60		30	45	ns
^t PHL	input low				19	30		26	40	ns
<u>tPLH</u>	G				25	40		21	40	٢ıs
^t PHL	3	0 8			33	50		34	50	ns
TPLH	DIR	A or B	(F		23	35		19	30	ns
^T PHL					25	40		27	45	ns

switching characteristics, V_{CC} = 5 V, T_A = 25° C

[†] These parameters are measured with the internal outputs state of the storage register opposite to that of the bus input. NOTE 2: Load circuits and voltage waveforms are shown in Section 1.





29-May-2015

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74LS646DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	Call TI	Level-1-260C-UNLIM	0 to 70	LS646	Samples
SN74LS646NT	LIFEBUY	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS646NT	
SN74LS646NT3	OBSOLETE	E PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SN74LS647DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74LS647NT	OBSOLETE	E PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SN74LS648NT	LIFEBUY	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS648NT	
SN74LS649NT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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PACKAGE OPTION ADDENDUM

29-May-2015

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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NT (R-PDIP-T**) 24 pins shown

PLASTIC DUAL-IN-LINE PACKAGE



All integrations are in minimeters. Dimensioning and toil
B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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